

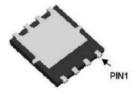
Features

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

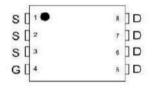
Product Summary

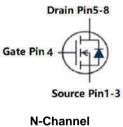
RoHs

VDS	60	V
R DS(on),Max@ VGS=10 V	8.5	mΩ
1 d	75	А



DFN5*6-8





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units		
V _{DS}	Drain-Source Voltage	Drain-Source Voltage 60			
Vgs	Gate-Source Voltage	±20	V		
I⊳@Tc=25°C	Continuous Drain Current, V _{GS} @ 10V ¹	Continuous Drain Current, $V_{GS} @ 10V^1$ 75			
I⊳@Tc=100°C	Continuous Drain Current, V _{GS} @ 10V ¹	47	A		
I _{DM}	Pulsed Drain Current ² 300		A		
EAS	Single Pulse Avalanche Energy ³	80	mJ		
las	Avalanche Current 40		A		
P₀@Tc=25°C	Total Power Dissipation ⁴	41	W		
Tstg	Storage Temperature Range -55 to 150		°C		
TJ	Operating Junction Temperature Range -55 to 150				

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	Thermal Resistance Junction-ambient ¹		62	°C/W
Rejc	Thermal Resistance Junction-case ¹		1.4	°C/W



Electrical Characteristics (T _J =25	°C, unless otherwise noted)
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Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V	
Provent	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =10A			8.5	mΩ	
Rds(on)	Static Drain-Source On-Resistance-	V _{GS} =4.5V , I _D =5A			12	mΩ	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2		2.5	V	
I	Drain Source Leekage Current	V _{DS} =48V , V _{GS} =0V , T _J =25°C			1		
IDSS	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =55°C			5	– uA	
lgss	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$			±100	nA	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.2		Ω	
Qg	Total Gate Charge (10V)			57			
Qgs	Gate-Source Charge	V _{DS} =30V , V _{GS} =10V , I _D =18A		8.7		nC	
Q_{gd}	Gate-Drain Charge			14			
T _{d(on)}	Turn-On Delay Time			16.2			
Tr	Rise Time	$V_{DD}=30V$, $V_{GS}=10V$, $R_{G}=3.3\Omega$,		41.2			
T _{d(off)}	Turn-Off Delay Time	I _D =20A		56.4		ns	
T _f	Fall Time			16.2			
Ciss	Input Capacitance			3307			
Coss	Output Capacitance	V _{DS} =30V , V _{GS} =0V , f=1MHz		201		pF	
Crss	Reverse Transfer Capacitance			151			

Diode Characteristics

Symbol	Parameter	eter Conditions		Тур.	Max.	Unit
ls	Continuous Source Current ^{1,5}	$V_G=V_D=0V$, Force Current			75	А
Vsd	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V
trr	Reverse Recovery Time	IF=20A , dI/dt=100A/µs ,		22		nS
Qrr	Reverse Recovery Charge	TJ=25°C		72		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =50V, V_{GS} =10V, L=0.1mH, I_{AS} =40A

4. The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

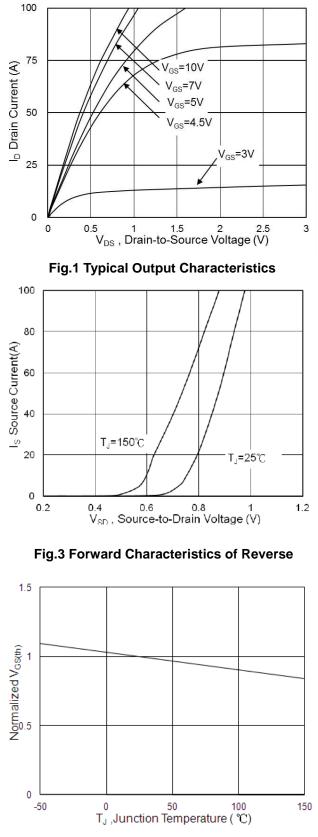


Fig.5 Normalized V_{GS(th)} vs T_J

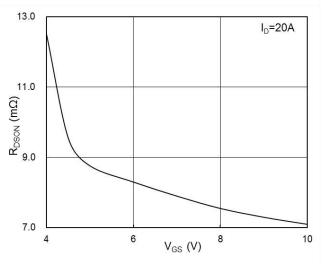


Fig.2 On-Resistance vs Gate-Source Voltage

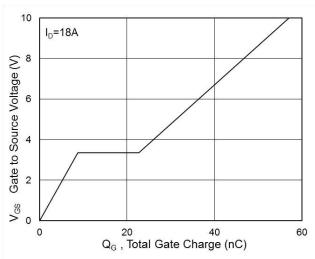


Fig.4 Gate-Charge Characteristics

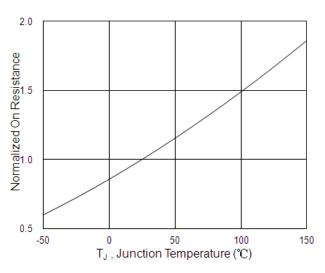


Fig.6 Normalized RDSON vs TJ



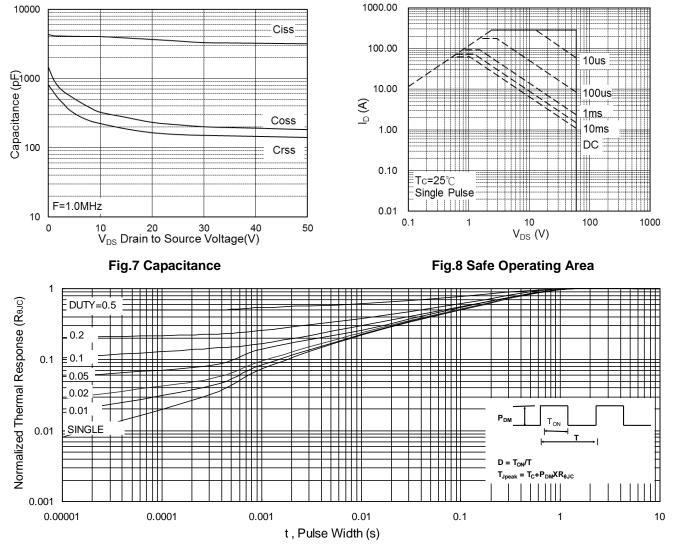


Fig.9 Normalized Maximum Transient Thermal Impedance

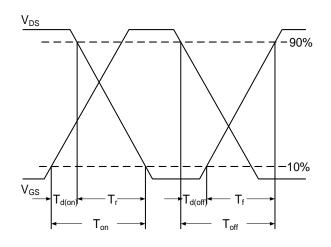


Fig.10 Switching Time Waveform

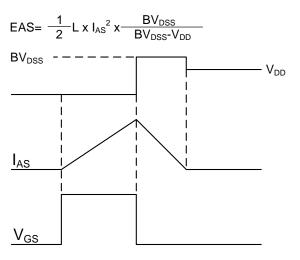
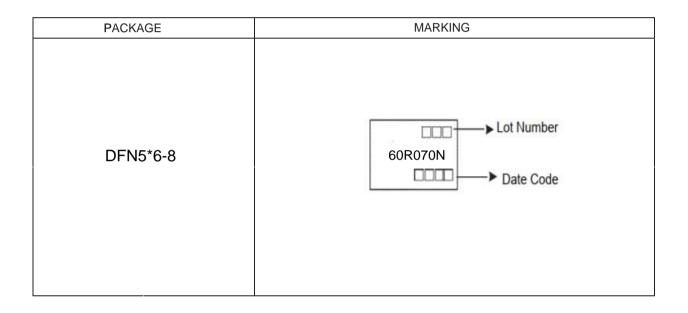


Fig.11 Unclamped Inductive Switching Waveform



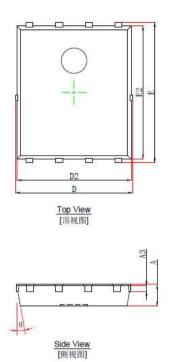
Ordering and Marking Information

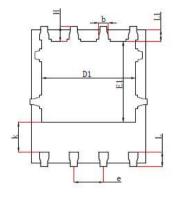
Ordering Device No.	Marking	Package	Packing	Quantity
JMN60R070NQ-R	60R070N	DFN5*6-8	Tape&Reel	4000/Reel





DFN5x6_P, 8 Leads





<u>Bottom View</u> [背视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	0.900	1.000	0.035	0.039	
A3	0.254	REF.	0.010	REF.	
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	3.910	4.110	0.154	0.162	
E1	3.375	3.575	0.133	0.141	
D2	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
e	1.270TYP.		0.050TYP.		
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	10°	12°	10°	12°	



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